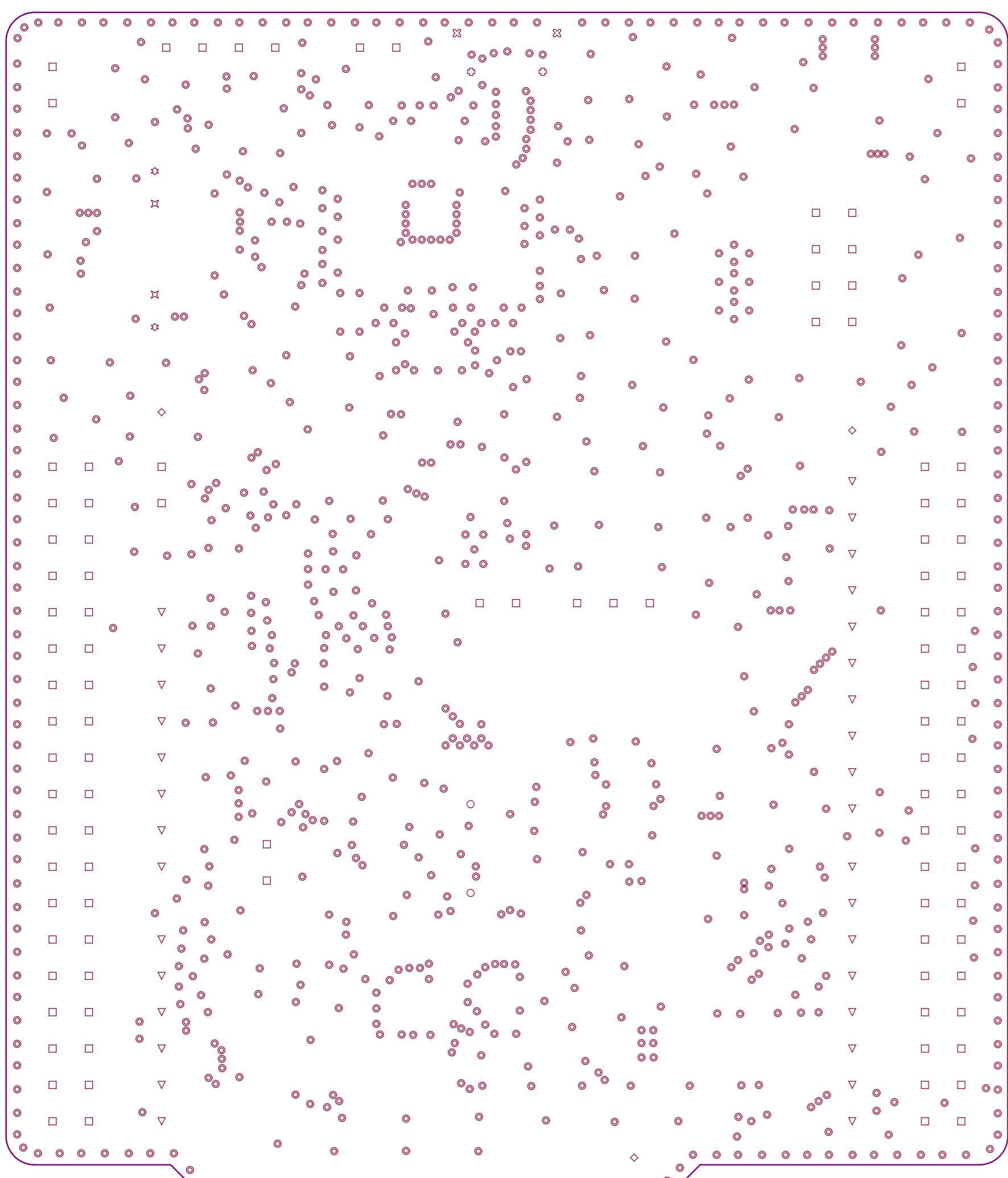


« THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE
WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY) »

PCB SPECIFICATIONS :

A. MATERIAL :	FR-4	<input type="checkbox"/> TG-170	<input checked="" type="checkbox"/> TG-150	<input type="checkbox"/> TG-140	**Plating type : lead Gold
B. MATERIAL FAMILY :	N/A				
C. SOLDERMASK COLOR :	<input type="checkbox"/> GREEN	<input checked="" type="checkbox"/> WHITE	<input type="checkbox"/> RED	<input type="checkbox"/> BLACK	
D. SILKSCREEN COLOR :	<input type="checkbox"/> WHITE	<input type="checkbox"/> YELLOW	<input type="checkbox"/> BLACK	<input checked="" type="checkbox"/> Blue ink PANTONE 2955	
E. SURFACE FINISH :	<input checked="" type="checkbox"/> ENIG	<input type="checkbox"/> IMMERSION SILVER		<input type="checkbox"/> IMMERSION TIN	
F. IMPEDANCE CONTROL :	<input type="checkbox"/> NO	<input checked="" type="checkbox"/> YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)			
G. THROUGH VIA :	PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.				
H. STACK-UP :	PLUG MATERIAL : <input checked="" type="checkbox"/> SOLDERMASK <input type="checkbox"/> NON-CONDUCTIVE EPOXY. SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.015mm	3.5	
1	Top Layer		0.042mm		
	Dielectric 1	PP-IT-180A	0.106mm	4.2	
2	Signal Layer 1		0.035mm		
	Dielectric 2	FR4	1.248mm	4.2	
3	Signal Layer 2		0.035mm		
	Dielectric 3	PP-IT-180A	0.106mm	4.2	
4	Bottom Layer		0.042mm		
	Bottom Solder	Solder Resist	0.015mm	3.5	
	Bottom Overlay				

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.120mm
GAPS : 0.120mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length	Routed Path Length
◎	920	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-	-
✗	2	0.600mm (23.62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	1.300mm (51.18mil)	0.700mm (27.56mil)
✚	2	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
❖	2	0.970mm (38.19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
○	2	1.000mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
□	103	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
▽	32	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	-	-
❖	2	1.190mm (46.85mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
◇	3	3.200mm (125.98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-	-
	1068 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

IMPEDANCE TABLE

LAYER	TRACE (mm)	SPACING (mm)	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	0.160	0.226	NA	90 ohm	+/- 10%